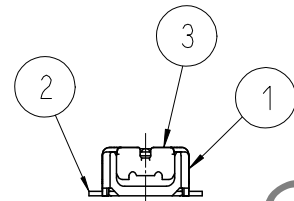
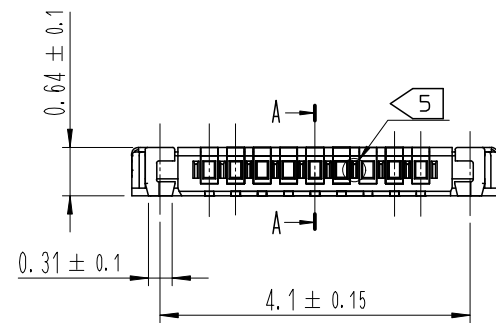
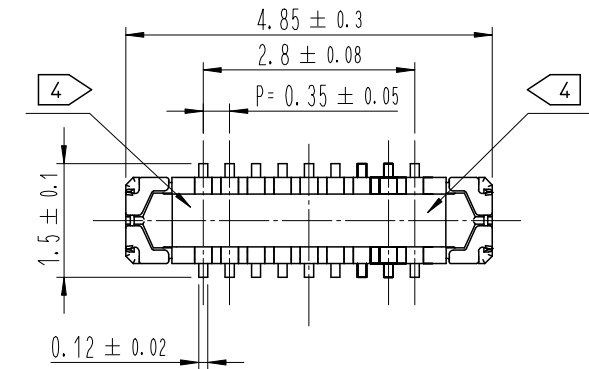
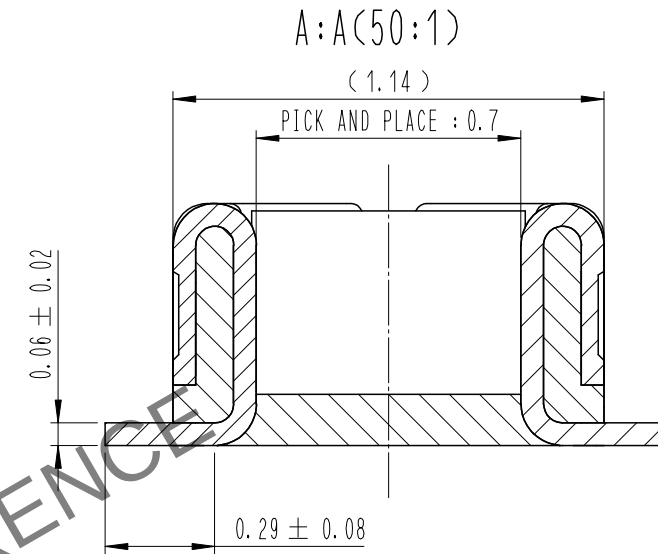


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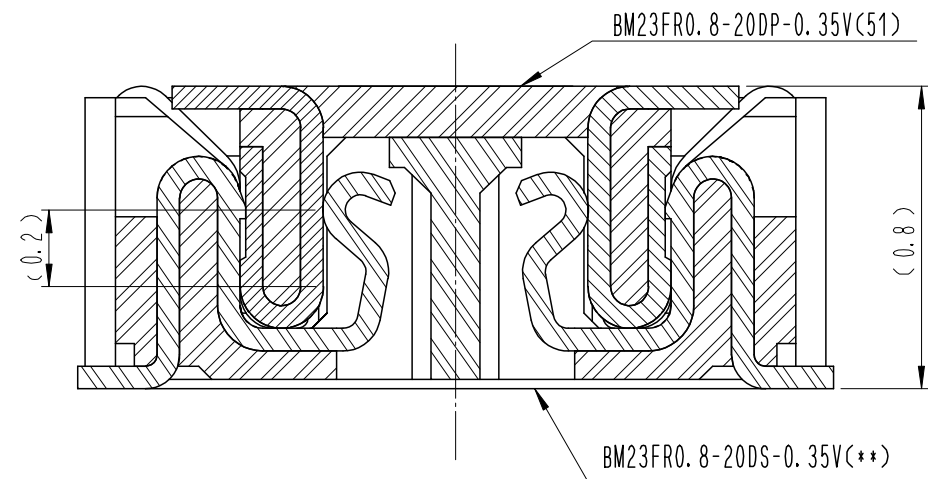


- NOTE
- 1. ALL LEAD CO-PLANARITY SHALL BE 0.08mm MAX.
 - 2. CONTACT PLATING SPECIFICATIONS.
CONTACT AREA : GOLD 0.05 μ m MIN.
SMT LEAD : GOLD 0.05 μ m MIN.
UNDER PLATING : NICKEL 1 μ m MIN.
(SURFACE : SEALING)
 - 3. METAL FITTING PLATING SPECIFICATIONS.
SMT LEAD : GOLD 0.05 μ m MIN.
UNDERPLATING : NICKEL 1 μ m MIN.
(SURFACE : SEALING)
 - 4. HRS MARK AND CAV No. ARE INDICATED IN APPROX POSITION SHOWN.
 - 5. A PART OF THE WALL COULD BE NOTCHED.

	COUNT	DESCRIPTION OF REVISIONS	B	Y	CHKD	DATE		COUNT	DESCRIPTION OF REVISIONS	B	Y	CHKD	DATE
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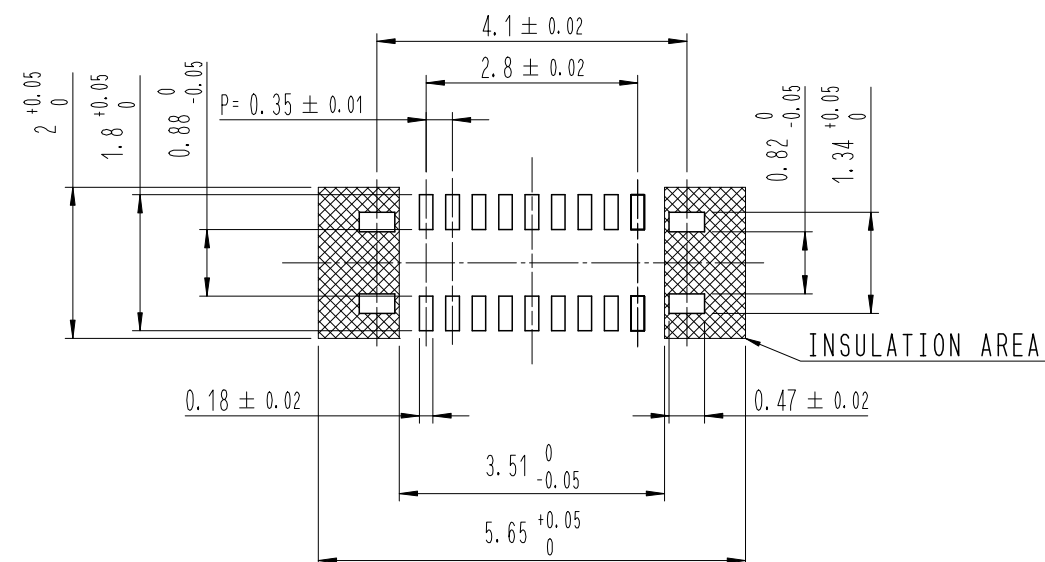
ENGAGEMENT FIGURE (50:1)



4	PS	CLEAR (EMBOSSED CARRIER TAPE)			
3	PHOSPHOR BRONZE	3			
2	PHOSPHOR BRONZE	2	6	PS	BLACK (PLASTIC REEL)
1	LCP	UL94 V-0, BLACK	5	POLYESTER	CLEAR (COVER TAPE)
NO.	MATERIAL	FINISH , REMARKS	NO.	MATERIAL	FINISH , REMARKS
REMARKS			DRAWN	DESIGNED	CHECKED
			S. H. JUNG	S. H. JUNG	H. W. JO
			16. 09. 09	16. 09. 09	16. 09. 09
			APPROVED	RELEASED	
			T. S. KANG	16. 09. 09	16. 09. 09
CODE NO. (OLD)	SCALE	DRAWING NO.	PART NO.		
	10:1	EDC3-632354	BM23FR0.8-18DP-0.35V(51)		
	UNITS	HRS HIROSE KOREA CO., LTD.	CODE NO		
	mm		CL 6644-0090-7-051		
					1/3

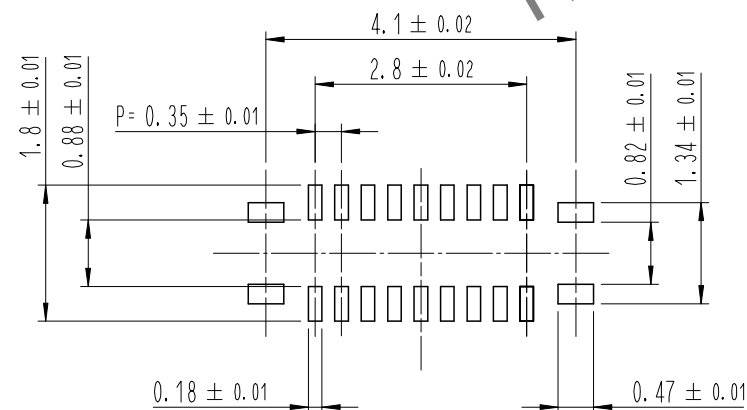
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7 RECOMMENDED PCB LAYOUT

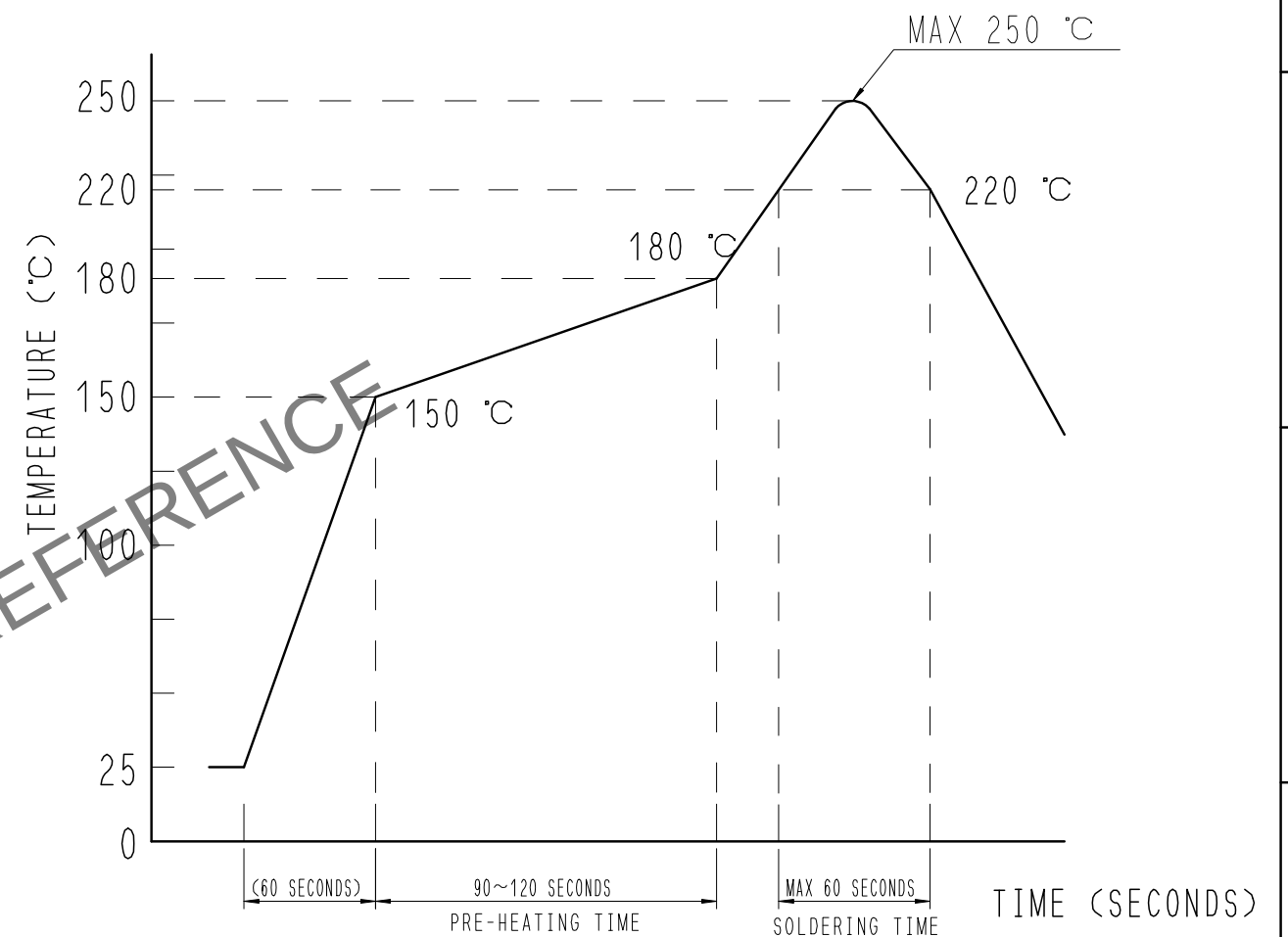


RECOMMENDED METAL MASK DIMENSIONS

METAL MASK THICKNESS : 100 μm



6 RECOMMENDED REFLOW TEMPERATURE PROFILE USING LEAD-FREE SOLDER PASTE.



REFLOW METHOD: N₂ REFLOW
NUMBER OF REFLOW CYCLES: 2 CYCLES MAX.
1) REFLOW TIME
DURATION ABOVE 220°C: 60 SEC MAX.
(PEAK TEMPERATURE: 250°C MAX)
2) PRE-HEAT TIME
PRE-HEAT TEMPERATURE (MIN): 150°C
PRE-HEAT TEMPERATURE (MAX): 180°C
PRE-HEAT TIME: 90-120 SEC.

- 6 THIS TEMPERATURE PROFILE IS PER THE CONDITIONS SHOWN ABOVE. ADDITIONAL FACTORS, SUCH AS SOLDER PASTE TYPE, PCB SIZE AND OTHER MOUNTED COMPONENTS COULD AFFECT THE PROFILE, THEREFORE, A THOROUGH EVALUATION OF MOUNTING CONDITION IS REQUIRED PRIOR TO PRODUCTION. TEMPERATURE IS MEASURED AT CONTACT LEAD.
- 7 PLEASE CONTACT US IN CASE YOU WILL MAKE DIFFERENT SETTINGS FROM OUR RECOMMENDATION.

	DRAWING NO.	EDC3-632354	PART NO.	BM23FR0.8-18DP-0.35V(51)	
	SCALE	10:1	CODE NO	CL 6644-0090-7-051	2/3
	UNITS	mm	HIROSE KOREA CO., LTD.		

